

Features

- Frequency: 6~18GHz
- Psat: 40dBm
- P.A.E.:20%
- Power Gain: 16dB
- CW

Electrical Specification (TA=+25°C, Vd=+28V, Vg=-1.6V, CW)

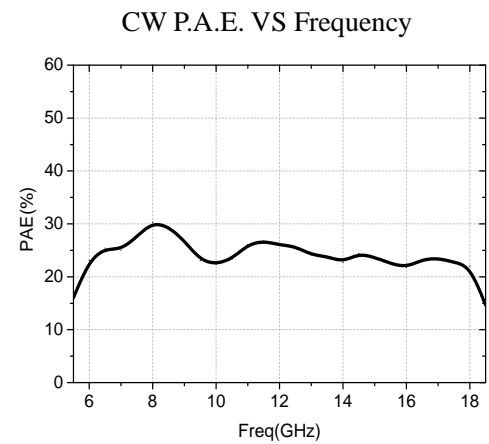
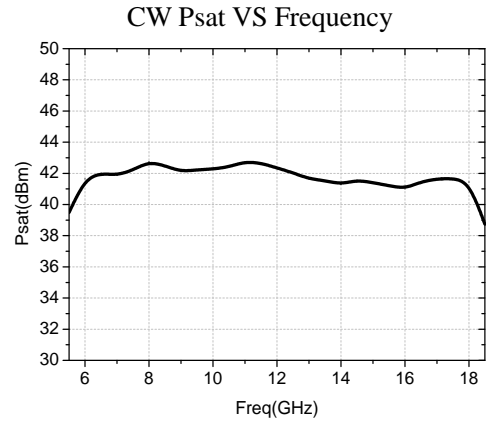
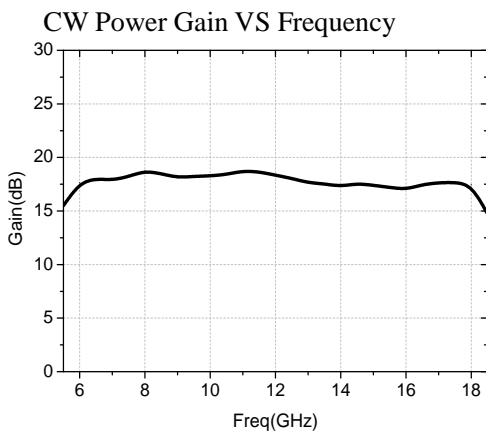
Parameter	Min.	Typ.	Max.	Unit
Frequency	6-18			GHz
Psat	40	41	-	dBm
P.A.E.	20	25	-	%
Power Gain	16	17	-	dB
VSWRin	-	2.5	-	—
Dynamic Operating Current		2.2		A

Note: 1) All chips have been on-chip 100% DC and RF tested .
2)RF Test Condition: Vd=28V, Vg=-1.6V.

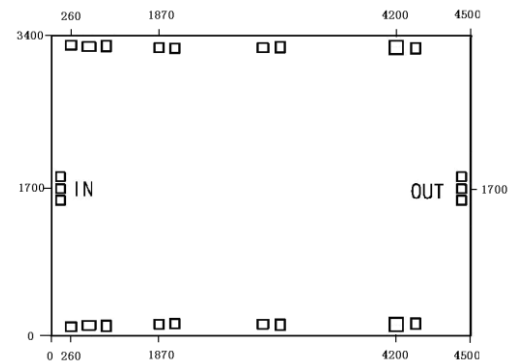
Limited Rating Values

Max Input Vd	+32V
Max Input Power	+30dBm
Storage Temperature	-65°C ~ +150°C
Operating Temperature	-55°C ~ +125°C

Typical Testing Curves

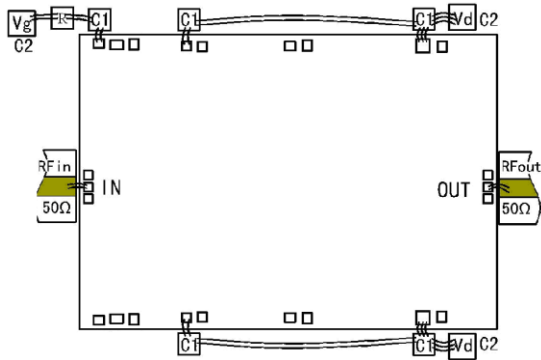


Dimensions and Outline



Note: The unit is um. Dimension of Input/Output Pad: 100×100um².

Assembly Diagram



Note: External capacitor $c1=100\text{pF}$, $c2=0.01\mu\text{F}$, $R=50\Omega$. Diameter of bonding wires is $25\mu\text{m}$.

Attention

- 1) 2 bonding wires should be used for Input/Output. The length of the wires should be shorter than $350\mu\text{m}$.
- 2) Bonding with 80/20 Au/Sn. The bonding temperature should be lower than 300°C and the time should be less than 30 seconds.
- 3) Antistatic protection should be taken.